

# Successful international validation test shipment of the PIP-II HB650 cryomodule transportation system

*Monday 26 August 2024 16:00 (2 hours)*

The PIP-II Project will receive fully assembled cryomodules from CEA and STFC-UKRI as in-kind contributions. Damage to these cryomodules during transport is understood to be a significant risk to the project, so an extensive testing and validation program has been executed to mitigate this risk. The centerpiece of this effort was the successful shipment, from FNAL to STFC-UKRI and back, of a prototype HB650 cryomodule with cold testing before and after shipment to verify no functionality changes from shipment. Building on an escalating test transport program, the prototype cryomodule was shipped to the UK and back using realistic logistics, handling, instrumentation, and planning. The process of executing this shipment, lessons learned, and plan moving forward will be presented here.

## Footnotes

## Funding Agency

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**Primary author:** HOLZBAUER, Jeremiah (Fermi National Accelerator Laboratory)

**Co-authors:** WIXSON, Adam (Fermi National Accelerator Laboratory); OZELIS, Joseph (Fermi National Accelerator Laboratory); HELSPER, Josh (Fermi National Accelerator Laboratory); KANE, Mitchell (Science and Technology Facilities Council)

**Presenter:** HOLZBAUER, Jeremiah (Fermi National Accelerator Laboratory)

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